

中文摘要

隨著資訊科技的進步，高儲存密度及高速度的資料存取的需求也逐漸升高，而光儲存科技在其中扮演著相當重要的角色，其微型化及輕量化的應用也使得光儲存系統更具有競爭力，而微光機電系統正好是製造更小更輕的光儲存系統的方法之一。

微機電製程技術在半導體科技的進步之下日漸成熟，以其製作的微光學讀取頭乃是實現可攜式且高容量的關鍵技術之一，於本論文中所提到的微光學讀取頭是由微光學平台及可控式聚焦微透鏡所組成，其中的聚焦微透鏡正是本論文所研究的重點。

聚焦微透鏡有兩種，一種是繞射式微透鏡，其製作方法較為容易但是效率並不高，另一種是折射式微透鏡，其製程較困難而效率高。而由於灰階光罩技術的發展，折射式微透鏡開始於微觀世界中嶄露頭角，但是製程中尚有厚度上的考量，所以本論文所採用的是此兩種方式的混合體 Fresnel 透鏡，Fresnel 透鏡是一種結構特殊介於折射型與繞射型微透鏡間的光學元件。

灰階光罩有許多不同的光罩製作方式，因為微影製程簡單，近年來備受矚目，有半階光罩、HEBS 玻璃灰階光罩，而在本論文中所採用的是以聚焦離子束將圖案刻印於灰階光罩上的氮化矽，進而利用來製作微透鏡，而微透鏡設計的大小是 100 微米，其數值孔徑為 0.65。

本論文的最終目標是能以聚焦離子束光罩做出微透鏡，並且能達到至少直徑為 600 微米的大小，以利能實現製作成微光學讀取頭之聚焦微透鏡，來整合整個微光學平台。

Abstract

As the progress of information technology, the demand of high capacity and high speed is increasing. Optical data storage technology plays a key role. The application of miniaturization and lightness makes the optical storage system more competitiveness. And Micro-Opto-Electro-Mechanical System (MOEMS) is one of these methods.

MEMS fabrication technology matures by the progress of the semiconductor technology, and micro optical pick-up head fabricated by this technology is one of the methods to realize portable high capacity. In this thesis, the micro optical pick-up head is composed of a micro optical bench and a controllable focusing lens bonded together. The focusing lens is main study in this thesis.

There are two kinds of focusing lens, one is the diffractive type with simple process and low efficiency, and another is the refractive type with complex process and high efficiency. However, as the gray-scale mask progress, the refractive type becomes attractive in micro size. Cause of the limitation of thickness, the hybrid of these two types, Fresnel lens was used. The Fresnel is a special optical component between the refractive and diffractive type.

There are many different mask fabrication process in gray-scale mask, such as the half tone and High Energy Beam Sensitive (HEBS) glass gray-scale mask, and is attractive recently due to the simple lithography process. The gray scale mask to fabricate focusing microlens was made by FIB milling pattern on silicon nitride. The size of the design microlens is $100\mu\text{m}$, and the numerical aperture is 0.65.

Final target in the thesis is to fabricate microlens by FIB mask, and the size of microlens can reach at least $600\mu\text{m}$ in diameter. In order to realize the focusing microlens of micro optical pick-up head to integrate the micro optical bench.

誌 謝

在這短短的兩年碩士生涯當中，雖稱不上有大智慧的啟發，也獲益良多。而這本論文能夠完成，首先要感謝指導教授邱一老師的殷殷指導，並於課業及研究上給予相當大的輔助與啟發，不僅僅是知識上的協助，亦教導我許多的做事應有的態度以及精神，使我不斷的成長茁壯。謝謝您，老師！

接下來要感謝的是無怨無悔地養育我的父母親，讓我也能毫無顧慮的學習研究，也是你們的支持與鼓勵讓我有動力持續下去，而妹妹雅如及弟弟智強也謝謝你們為我加油打氣。

感謝企桓學長給予我的指導及幫助，讓我實驗順利，感謝學長指導許多作事情的方法及生活上的見聞，感謝實驗室中的每一個人，學長俊毅、嘉豪、依纖感謝你們的經驗指導，同學文中、志偉、育杉感謝你們的陪伴及幫忙，學弟建勳、忠衛、炯廷、均宏的支持與打氣，感謝室友樹德、建煌這兩年的陪伴，有許多的美好回憶都是由你們參予貢獻的，能與你們在一起真的非常開心。

最後，懷著喜悅的心情將此論文獻給我的家人、同學、朋友以及所有曾經幫助過我的人，謝謝你們，也希望將來有機會再相聚。期許自己能在未知的將來奉獻所學，回饋社會。

許英傑 謹識

中華民國九十四年十月

新竹 交大

Table of Content

中文摘要	i
Abstract	ii
誌謝	iii
Table of Content	iv
List of Figures	vi
List of Tables	ix
1 · Introduction	1
1-1 Motivation.....	1
1-2 Micro lens.....	4
1-2-1 Refractive Microlenses.....	5
1-2-2 Diffractive Microlenses.....	6
1-3 Microlens fabrication.....	9
1-3-1 Reflow Method.....	9
1-3-2 Binary Method.....	10
1-3-3 Gray Scale Technology.....	11
1-4 Thesis overview.....	17
2 · Principle and Design	18
2-1 Material property	18
2-1-1 Photoresist AZ4620.....	18
2-1-2 Silicon nitride.....	21
2-2 Lens design.....	23
2-3 Binary design.....	27
2-4 FIB mask design.....	30

3 · Fabrication	33
3-1 Binary microlens process.....	33
3-2 Film mask process.....	35
3-3 HEBS mask process.....	36
3-4 FIB mask and microlens fabrication process.....	39
4 · Measurement	41
4-1 FIB mask measurement.....	41
5 · Conclusion	48
5-1 Conclusion.....	48
5-2 Future work.....	48
Reference	49



List of Figures

Figure 1-1 Conventional optical pick-up head.....	2
Figure 1-2 Scanning electron micrograph of the free-space integrated optical disk pickup head.....	3
Figure 1-3 MEMS based optical pick-up head.....	4
Figure 1-4 Different types of Microlenses	4
Figure 1-5 Schematic of an out-of-plane refractive microlens.....	5
Figure 1-6 Blazing of a lens results in a reduced thickness.....	7
Figure 1-7 Schematic of (a) a continuous relief Fresnel zone plate, (b) a multiple-step binary microlens.....	7
Figure 1-8 SEM of an out-plane binary Fresnel microlens.....	8
Figure 1-9 Laser-beam-direct-writing microlens, where the lens radius is 106 μm with a N.A. of 0.21.....	9
Figure 1-10 Reflow process for refractive microlens.....	10
Figure 1-11 Fabrication process of the binary method.....	11
Figure 1-12 The schematic of the halftone mask.....	12
Figure 1-13 Example of a three-level gray-scale mask pattern and the resulting photoresist structure.....	12
Figure 1-14 Three gray levels patterned in AZ 4620 photoresist resulting from a similar mask pattern in Figure 1-13.....	13
Figure 1-15 Diffractive microlens array (a) on HEBS mask (b) on polymer.....	14
Figure 1-16 Nominal 30 μm diameter fused silica microtube by FIB milling....	15
Figure 1-17 SEM of a six facet cutting tool for ultraprecision machining.....	15
Figure 1-18 Typical FIB schematic.....	17

Figure 2-1 Solubility versus the transmittance for the photoresist samples.....	20
Figure 2-2 Solubility plotted versus the transmittance for the AZ4620 samples.	21
Figure 2-3 (a)Refractive index of LPCVD silicon nitride, (b)extinction coefficient.....	22
Figure 2-4 Diagram for the Lensmaker's Formula.....	24
Figure 2-5 Diagram of the numerical aperture	24
Figure 2-6 Design of the microlens (aperture : $60\mu\text{m}$).....	26
Figure 2-7 Design of the microlens (aperture : $100\mu\text{m}$).....	26
Figure 2-8 Intensity profile and contour plot of an optical beam collimated by a binary micro-Fresnel lens.....	27
Figure 2-9 Processing cycles of multi-level binary-optics microlens.....	28
Figure 2-10 Fresnel lens (a) first step mask (b) second step mask.....	30
Figure 2-11 Gray-scale of the FIB pattern (aperture = $60\mu\text{m}$).....	31
Figure 2-12 Gray-scale of the FIB pattern (aperture = $100\mu\text{m}$).....	32
Figure 3-1 Fabrication process of binary mask.....	33
Figure 3-2 Schematic of the film test mask	35
Figure 3-3 Roughness of the test pattern with test mask.....	36
Figure 3-4 Relation of etch depth to transmittance of the film mask.....	36
Figure 3-5 (a) Profile measurement by SEM, (b) profile measurement by WYKO Interferometer, (c) profile measurement by ET-4000, and (d) roughness by WYKO	37
Figure 3-6 Fabrication process of the FIB mask and the microlens.....	40
Figure 4-1 Pattern on the FIB mask.....	41
Figure 4-2 Etched test pattern measurement	42
Figure 4-3 (a) Test pattern measurement by AFM, (b) 3D view with 180°	

rotation.....	43
Figure 4-4 Depth of the test pattern	43
Figure 4-5 2D profile measurement of Si ₃ N ₄ by FIB milling.....	44
Figure 4-6 (a) Designed profile, (b) AFM profile after 20-minute FIB process, (c) compensated data, (d) AFM profile after 30-minute FIB process, (e) AFM profile after 75-minute FIB process.....	45
Figure 4-7 Maximum etched depth and step height of middle circle of silicon nitride.....	47
Figure 4-8 Step height of first ring and etched depth of middle circle of silicon nitride.....	47



List of Tables

Table 2-1 Calculation of the lens design.....	25
Table 2-2 Calculated values of sliced microlens.....	27

